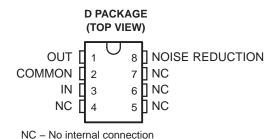
SGLS252A - AUGUST 2004 - REVISED JUNE 2008

- **Qualified for Automotive Applications**
- 1/2 V_I Virtual Ground for Analog Systems
- Micropower Operation . . . 170 μA Typ, $V_1 = 5 V$
- Wide VI Range . . . 4 V to 40 V
- **High Output-Current Capability**
 - Source . . . 20 mA Typ
 - Sink . . . 20 mA Typ
- **Excellent Output Regulation**
 - $-102 \,\mu\text{V}$ Typ at $I_{O} = 0$ to $-10 \,\text{mA}$
 - $+49 \mu V$ Typ at $I_0 = 0$ to +10 mA
- Low-Impedance Output . . . 0.0075 Ω Typ
- **Noise Reduction Pin**

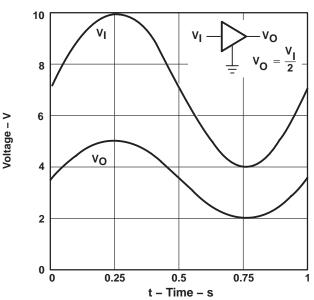
description

In signal-conditioning applications utilizing a single power source, a reference voltage equal to one-half the supply voltage is required for termination of all analog signal grounds. Texas Instruments presents a precision virtual ground whose output voltage is always equal to one-half the input voltage, the TLE2426 rail splitter.

The unique combination of a high-performance, micropower operational amplifier and a precisiontrimmed divider on a single silicon chip results in a precise V_O/V_I ratio of 0.5 while sinking and sourcing current. The TLE2426 provides a low-impedance output with 20 mA of sink and



INPUT/OUTPUT TRANSFER CHARACTERISTICS



source capability while drawing less than 280 µA of supply current over the full input range of 4 V to 40 V. A designer need not pay the price in terms of board space for a conventional signal ground consisting of resistors, capacitors, operational amplifiers, and voltage references. For increased performance, the 8-pin package provides a noise-reduction pin. With the addition of an external capacitor (CNR), peak-to-peak noise is reduced while line ripple rejection is improved.

Initial output tolerance for a single 5-V or 12-V system is better than 1% over the full 40-V input range. Ripple rejection exceeds 12 bits of accuracy. Whether the application is for a data acquisition front end, analog signal termination, or simply a precision voltage reference, the TLE2426 eliminates a major source of system error.

ORDERING INFORMATION[†]

TA	PACKA	GE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC (D)	Tape and Reel	TLE2426QDRQ1	2426Q1

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.



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SGLS252A - AUGUST 2004 - REVISED JUNE 2008

absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Continuous input voltage, V _I	
Continuous filter trap voltage	
Output current, I _O	±80 mA
Duration of short-circuit current at (or below) 25°C (see Note 1)	unlimited
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A : Q suffix	–40°C to 125°C
Storage temperature range, T _{stq}	–65°C to 150°C
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds: D package	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING
D	1102 mV	10.3 mW/°C	638.5 mW	484 mW	72.1 mW

recommended operating conditions

	MIN	MAX	UNIT
Input voltage, V _I	4	40	V
Operating free-air temperature, T _A	-40	125	°C



NOTE 1: The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.

electrical characteristics at specified free-air temperature, $V_I = 5 V$, $I_O = 0$ (unless otherwise noted)

PARAMETER	TEST CONDITIO	NS	T _A †	MIN	TYP	MAX	UNIT	
	V _I = 4 V			1.98	2	2.02		
Output voltage	V _I = 5 V	25°C	2.48	2.5	2.52	V		
	V _I = 40 V		19.8	20	20.2			
	V _I = 5 V	Full range	2.465		2.535			
Temperature coefficient of output voltage			Full range		25		ppm/°C	
		V _I = 5 V	25°C		170	300		
Supply current	No load	No load $V_{\parallel} = 4 \text{ to } 40 \text{ V}$				400	μΑ	
	1 01- 404		25°C		-0.102	±0.7		
Output voltage regulation (sourcing current)‡	IO = 0 to - 10 mA	$I_{O} = 0 \text{ to } -10 \text{ mA}$				±10	mV	
	$I_0 = 0 \text{ to } -20 \text{ mA}$	25°C		-0.121	±1.4			
Output voltage regulation (sinking current)‡	$I_O = 0$ to 10 mA	25°C		0.049	±0.5			
	$I_O = 0$ to 8 mA	Full range			±10	mV		
(Sinking current)	$I_O = 0$ to 20 mA	25°C		0.175	±1.4			
Output impedance‡			25°C		7.5	22.5	mΩ	
Noise-reduction impedance			25°C		110		kΩ	
Oh ant almost assument	Sinking current,	V _O = 5 V	0500		26		4	
Short-circuit current	Sourcing current,	VO = 0	25°C	ange 400 °C -0.102 ±0.7 ange ±10 °C -0.121 ±1.4 °C 0.049 ±0.5 ange ±10 °C 7.5 22.5 °C 110 °C -47 °C 30 °C 30 °C 290 C 275	mA			
Output a discoultant man	6 4011-1-40111-	$C_{NR} = 0$	0500	120		μV		
Output noise voltage, rms	f = 10 Hz to 10 kHz	C _{NR} = 1 μF	25°C	30				
	V 12 0 400 1 140 mA	C _L = 0	0500		290			
Output voltage current step response	V_{O} to 0.1%, $I_{O} = \pm 10 \text{ mA}$	C _L = 100 pF	25°C	275]		
	V= to 0.040/	C _L = 0	400			μs		
	V_{O} to 0.01%, $I_{O} = \pm 10 \text{ mA}$ $C_{L} = 100 \text{ pF}$		25°C	390				
Ston response	$V_I = 0 \text{ to } 5 \text{ V}, V_O \text{ to } 0.1\%$	C _I = 100 pF	25°C		20			
Step response	$V_I = 0 \text{ to } 5 \text{ V}, V_O \text{ to } 0.01\%$	25 0	120			μs		

[†] Full range is –40°C to 125°C. ‡ The listed values are not production tested.

TLE2426-Q1 THE "RAIL SPLITTER" PRECISION VIRTUAL GROUND SGLS252A - AUGUST 2004 - REVISED JUNE 2008

electrical characteristics at specified free-air temperature, V_{I} = 12 V, I_{O} = 0 (unless otherwise noted)

PARAMETER	TEST CONDITIONS TAT MIN		TYP	MAX	UNIT			
	V _I = 4 V		1.98	2	2.02	· v		
Cutant valta as	V _I = 12 V	25°C	5.95	6	6.05			
Output voltage	V _I = 40 V		19.8	20	20.2			
	V _I = 12 V		Full range	5.925		6.075		
Temperature coefficient of output voltage			Full range		35		ppm/°C	
Complex compact	No load	V _I = 12 V	25°C		195	300	4	
Supply current	Supply current No load		Full range			400	μΑ	
	L 0.15 40 A		25°C		-1.48	±10		
Output voltage regulation (sourcing current)‡	$I_{O} = 0 \text{ to } -10 \text{ mA}$		Full range			±10	mV	
(Sourcing current)+	$I_{O} = 0 \text{ to } -20 \text{ mA}$	25°C		-3.9	±10			
	I _O = 0 to 10 mA	25°C		2.27	±10			
Output voltage regulation (sinking current)‡	I _O = 0 to 8 mA	Full range			±10	mV		
	I _O = 0 to 20 mA	25°C		4.3	±10			
Output impedance [‡]			25°C		7.5	22.5	mΩ	
Noise-reduction impedance			25°C		110		kΩ	
	Sinking current, V _O = 12 V		0500		31		mA	
Short-circuit current	Sourcing current,	V _O = 0	25°C		-70			
		$C_{NR} = 0$	0500		120		μV	
Output noise voltage, rms	f = 10 Hz to 10 kHz	C _{NR} = 1 μF	25°C		30			
	V + 0.40′ L + 40 A	C _L = 0	0500		290			
	V_{O} to 0.1%, $I_{O} = \pm 10 \text{ mA}$	C _L = 100 pF	25°C		275			
Output voltage current step response	V . 0.0404 L . 40 A	C _L = 0	0500		400		μs	
	V_{O} to 0.01%, $I_{O} = \pm 10 \text{ mA}$	C _L = 100 pF	25°C		390			
Cton recononce	$V_{I} = 0 \text{ to } 12 \text{ V}, V_{O} \text{ to } 0.1\%$ $V_{I} = 0 \text{ to } 12 \text{ V}, V_{O} \text{ to } 0.01\%$ $C_{L} = 100 \text{ pF}$		0500		12			
Step response			25°C		120		μs	



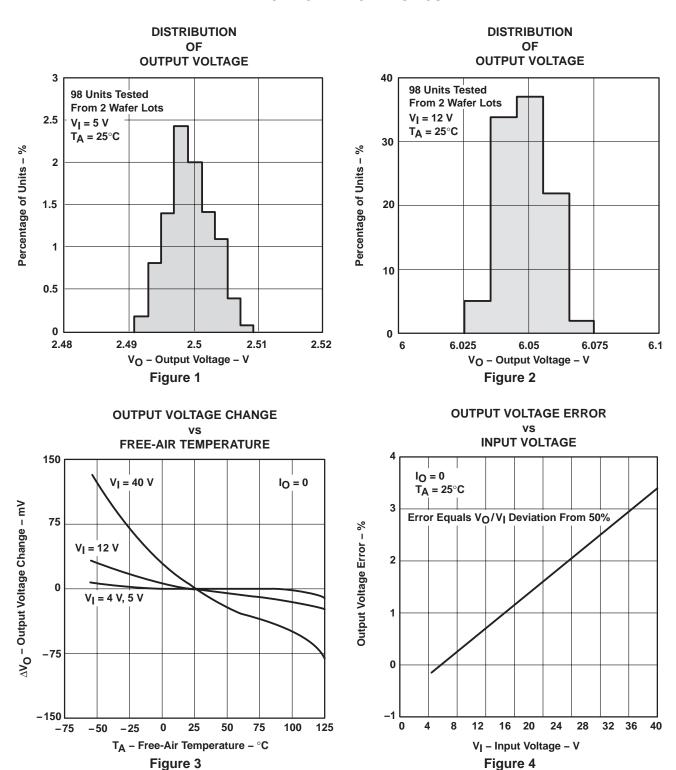
[†] Full range is –40°C to 125°C. ‡ The listed values are not production tested.

TYPICAL CHARACTERISTICS

Table Of Graphs

		FIGURE
Output voltage	Distribution	1, 2
Output voltage change	vs Free-air temperature	3
Output voltage error	vs Input voltage	4
Level bire comment	vs Input voltage	5
Input bias current	vs Free-air temperature	6
Output voltage regulation	vs Output current	7
Output impedance	vs Frequency	8
Obsert einseit sedent sement	vs Input voltage	9, 10
Short-circuit output current	vs Free-air temperature	11, 12
Ripple rejection	vs Frequency	13
Spectral noise voltage density	vs Frequency	14
Output voltage response to output current step	vs Time	15
Output voltage power-up response	vs Time	16
Output current	vs Load capacitance	17

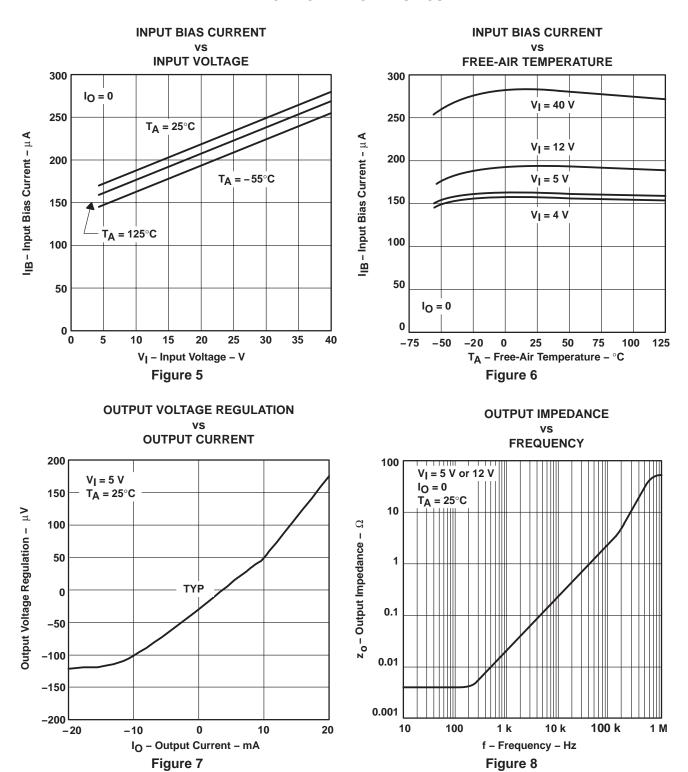
TYPICAL CHARACTERISTICS[†]



[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.



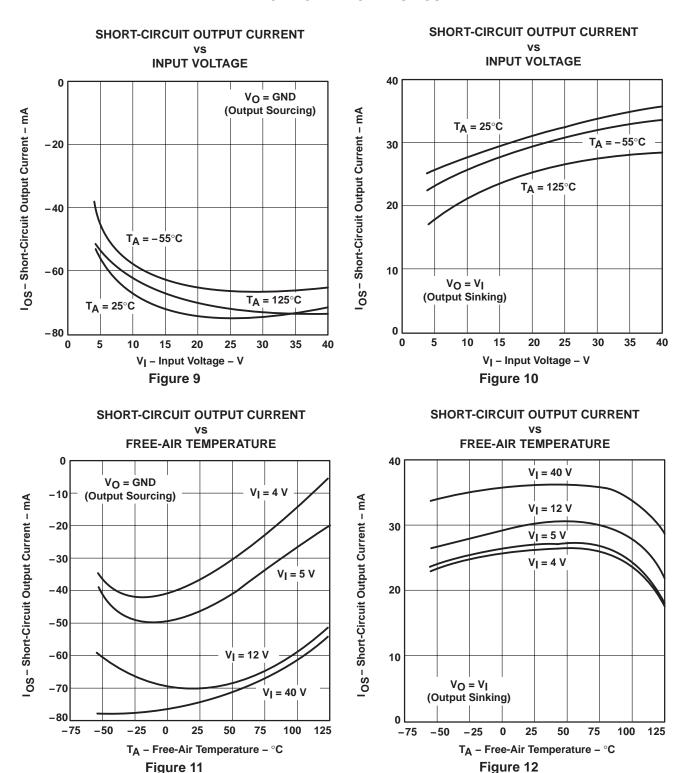
TYPICAL CHARACTERISTICS[†]



[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS[†]



[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS

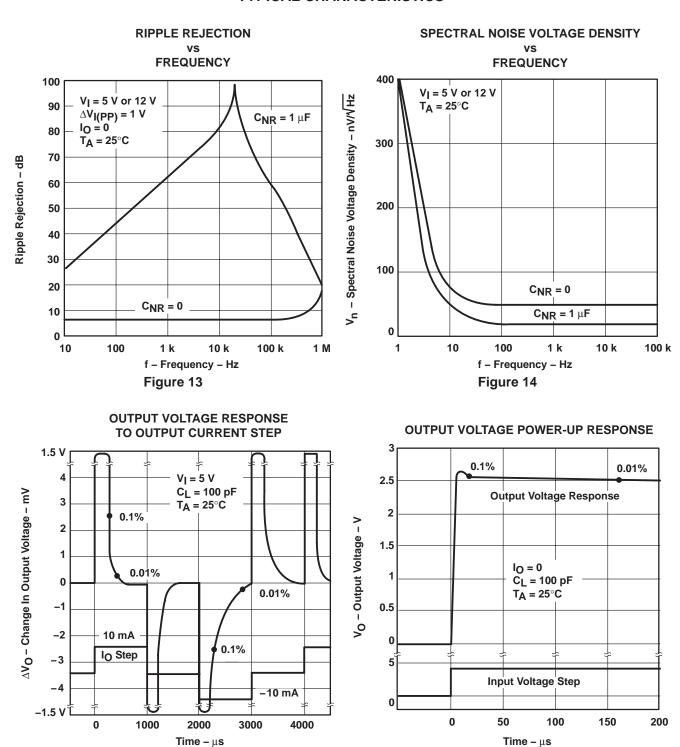




Figure 15

Figure 16

TYPICAL CHARACTERISTICS

STABILITY RANGE OUTPUT CURRENT VS

LOAD CAPACITANCE

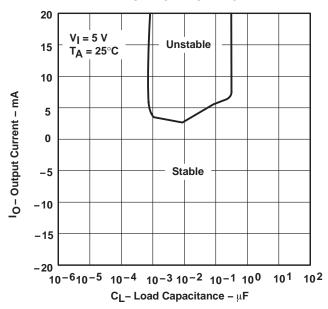


Figure 17



MACROMODEL INFORMATION

```
TLE2426 OPERATIONAL AMPLIFIER "MACROMODEL" SUBCIRCUIT
   CREATED USING PARTS RELEASE 4.03 ON 08/21/90 AT 13:51
                 SUPPLY VOLTAGE: 5 V
   REV (N/A)
   CONNECTIONS:
                    FILTER
                        INPUT
                           COMMON
                               OUTPUT
.SUBCKT TLE2426
                               5
   C1
          11 12 21.66E-12
   C2
              7 30.00E-12
   C3
          87
              0 10.64E-9
   CPSR
          85 86 15.9E-9
   DCM+
          81 82 DX
   DCM-
          83
             81 DX
   DC
           5
             53 DX
   DE
          54
              5 DX
   DLP
             91 DX
          90
   DLN
          92
             90
                DX
   DP
           4
              3 DX
   ECMR
          84
             99 (2,99) 1
                           (3,0) (4,0) 0 .5 .5
(3,4) -16.22E-6 3.24E-6
   EGND
          99
              0 POLY(2)
          85
   EPSR
              0
                POLY(1)
   ENSE
              2 POLY(1)
                           (88,0) 120E-61
   FΒ
           7
             99 POLY(6)
                           VB VC VE VLPVLNVPSR 0 74.8E6 - 10E6 10E6 10E6 - 10E6 74E6
   GA
           6
              0
                11 12 320.4E-6
              6 10 99 1.013E-9
   GCM
           0
                 (85,86)
   GPSR
          85 86
                           100E-6
   GRC1
           4
             11
                 (4,11) 3.204E-4
                 (4,12) 3.204E-4
   GRC2
           4 12
   GRE1
          13 10 (13,10)
                          1.038E-3
   GRE2
          14 10 (14,10)
                           1.038E-3
              0 VLIM 1K
   HT.TM
          90
   HCMR
          80
             1 POLY(2)
                           VCM+
                                  VCM-
                                         0 1E2
                                                    1E2
   IRP
           3
              4 146E-6
   IEE
           3 10 DC 24.05E-6
   IIO
           2
             0.2E - 9
              0 1E-21
   T 1
          88
   Q1
          11
             89 13 QX
          12 80 14 QX
   02
   R2
           6
              9 100.0E3
          84
   RCM
             81 1K
   REE
          10 99
                 8.316E6
   RN1
          87
              0
                 2.55E8
          87
             88 11.67E3
   RN2
   RO1
           8
              5
                63
           7
             99 62
   RO2
   VCM+
          82
             99 1.0
   VCM-
          83
             99
                 -2.3
              0 DC 0
   VB
           9
   VC
           3
             53 DC 1.400
   VE
          54
              4 DC
                    1.400
           7
              8 DC
   VLIM
                    Ω
   VLP
          91
              0 DC 30
           0 92 DC
   VLN
                    30
   VPSR
           0
             86 DC
                    0
```



RFB

RTN1

RIN2

.ENDS

2 1K

3

1

.MODEL DX D(IS=800.OE-18)

1 220K

4 220K

.MODEL QX PNP(IS=800.OE-18BF=480)

6-.lan-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Samples
	(1)		Drawing			(2)		(3)	(Requires Login)
TLE2426QDRG4Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLE2426QDRQ1	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF TLE2426-Q1:

Catalog: TLE2426

■ Enhanced Product: TLE2426-EP

PACKAGE OPTION ADDENDUM

6-Jan-2013

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



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